



## N-Channel Enhancement MOSFET

### Features

- Drain-Source Breakdown Voltage  $V_{DSS}$  100V
- Drain-Source On-Resistance  
 $R_{DS(ON)}$  17mΩ, at  $V_{GS} = 10V$ ,  $I_D = 20A$   
 $R_{DS(ON)}$  20mΩ, at  $V_{GS} = 4.5V$ ,  $I_D = 16A$
- Continuous Drain Current at  $T_C = 25^\circ C$   $I_D = 28.1A$
- Advanced high cell density Trench Technology
- RoHS Compliance & Halogen Free

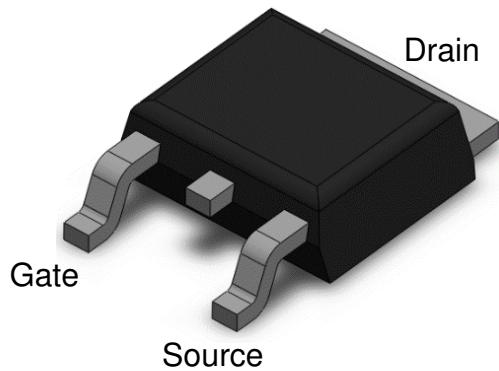
### Description

The CTL281NS10-T52 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application.

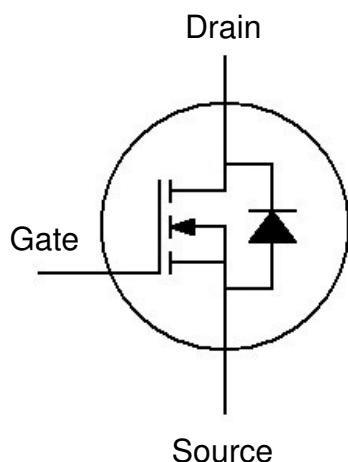
### Applications

- DC/DC Converter
- Load Switch
- LCD/LED Display inverter

### Package Outline



### Schematic





CTL281NS10-T52

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### Absolute Maximum Rating at 25°C

Symbol	Parameters	Test Conditions	Min	Note
V <sub>DS</sub>	Drain-Source Voltage	100	V	
V <sub>GS</sub>	Gate-Source Voltage	±20	V	
I <sub>D</sub>	Continuous Drain Current @T <sub>c</sub> =25°C	28.1	A	1
I <sub>DM</sub>	Pulsed Drain Current	112	A	1
P <sub>D</sub>	Total Power Dissipation @T <sub>c</sub> =25°C	27.8	W	2
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C	
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C	

### Thermal Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
R <sub>θJC</sub>	Thermal Resistance Junction-Case		--	--	4.5	°C /W	1,4



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Electrical Characteristics  $T_A = 25^\circ\text{C}$  (unless otherwise specified)

## Static Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$V_{BDSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu\text{A}$	100	-	-	V	
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	$\mu\text{A}$	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA	

## On Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$R_{DS(ON)}$	Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 20A$	-	17	22	$\text{m}\Omega$	3
		$V_{GS} = 4.5V, I_D = 16A$	-	20	26	$\text{m}\Omega$	3
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.0	-	3.0	V	3

## Dynamic Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$C_{iss}$	Input Capacitance	$V_{GS} = 0V,$ $V_{DS} = 15V$ $f = 1\text{MHz}$	-	4400	-	pF	
$C_{oss}$	Output Capacitance		-	286	-		
$C_{rss}$	Reverse Transfer Capacitance		-	233	-		

## Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$T_{D(ON)}$	Turn-On Delay Time	$V_{DS} = 50V, R_G = 4.7\Omega$ $V_{GS} = 10V, R_L = 1.5\Omega$	-	30.3	-	ns	
$T_R$	Rise Time		-	166	-		
$T_{D(OFF)}$	Turn-Off Delay Time		-	92.4	-		
$T_F$	Fall Time		-	186	-		
$Q_G$	Total Gate Charge	$V_{DS} = 80V,$ $V_{GS} = 5V,$ $I_D = 35A$	-	54.2	-	nC	
$Q_{GS}$	Gate-Source Charge		-	16.5	-		
$Q_{GD}$	Gate-Drain (Miller) Charge		-	20.8	-		



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### Drain-Source Diode Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V <sub>SD</sub>	Body Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 1A	-	-	1.3	V	1
I <sub>SD</sub>	Body Diode Continuous Current		-	-	1	A	1

Note:

1. The power dissipation is limited by 150°C junction temperature.
2. The data tested by pulsed , pulse width  $\leq$  300μs , duty cycle  $\leq$  2%
3. Thermal Resistance follow JESD51-3.



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### Typical Characteristic Curves

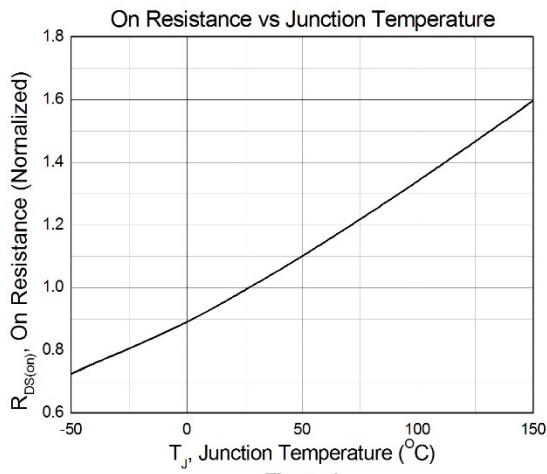


Figure 1

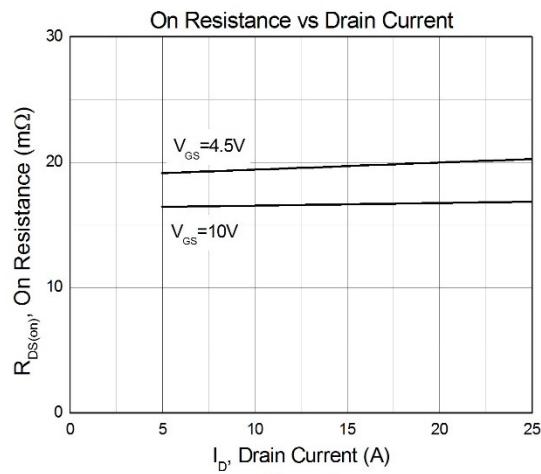


Figure 2

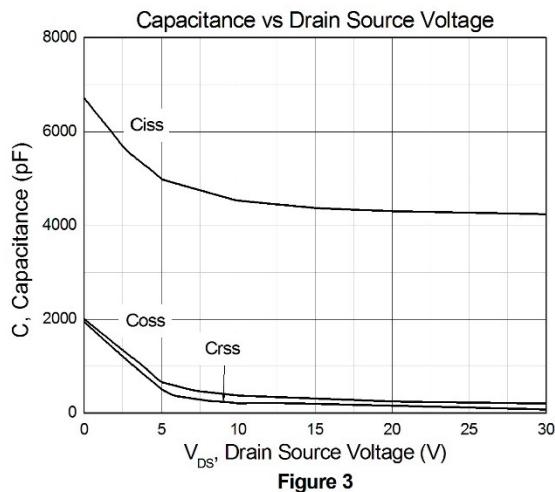


Figure 3

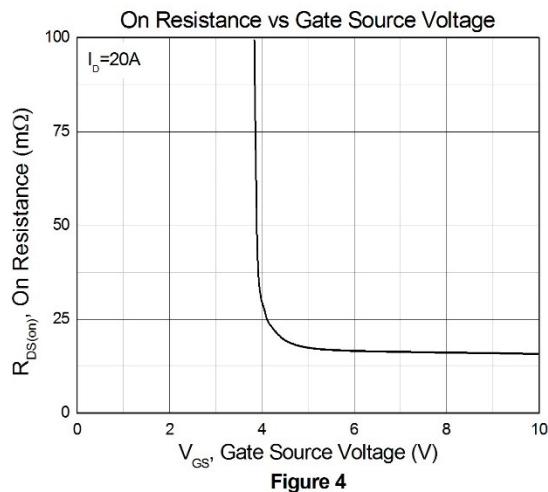


Figure 4

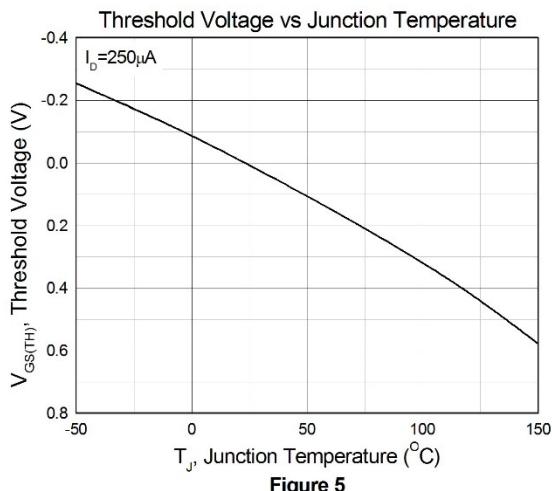


Figure 5

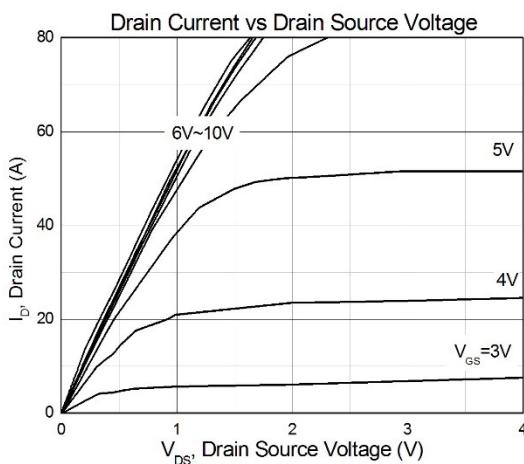


Figure 6



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## N-Channel Enhancement MOSFET

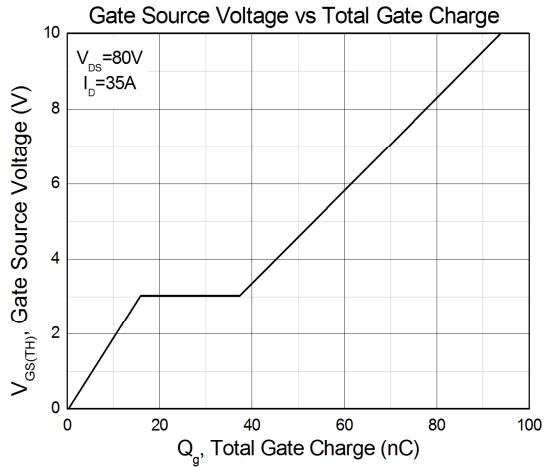


Figure 7

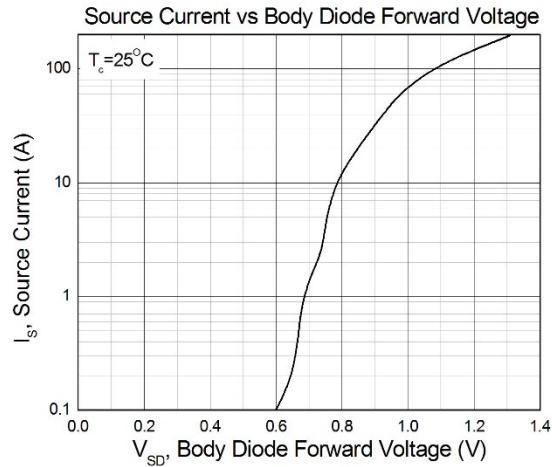


Figure 8



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## N-Channel Enhancement MOSFET

### Test Circuits & Waveforms

Figure 9: Gate Charge Test Circuit

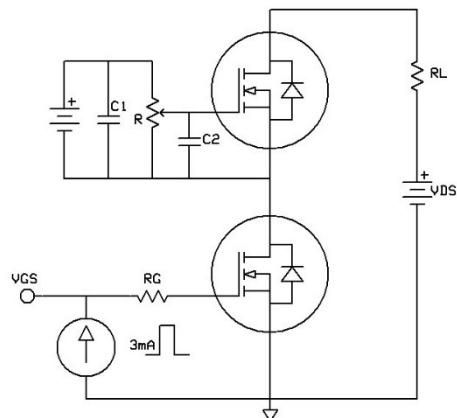


Figure 10: Gate Charge Waveform

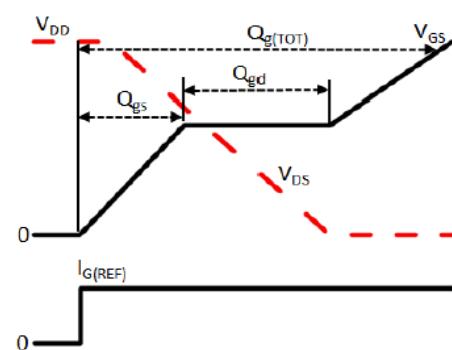


Figure 11: Switching Time Test Circuit

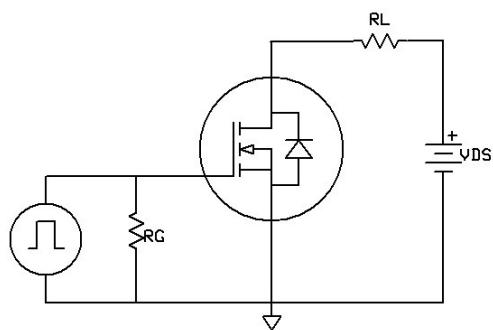
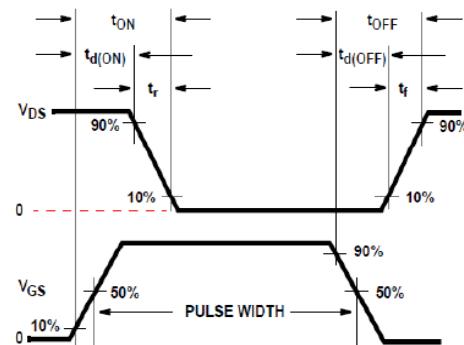


Figure 12: Switching Time Waveform

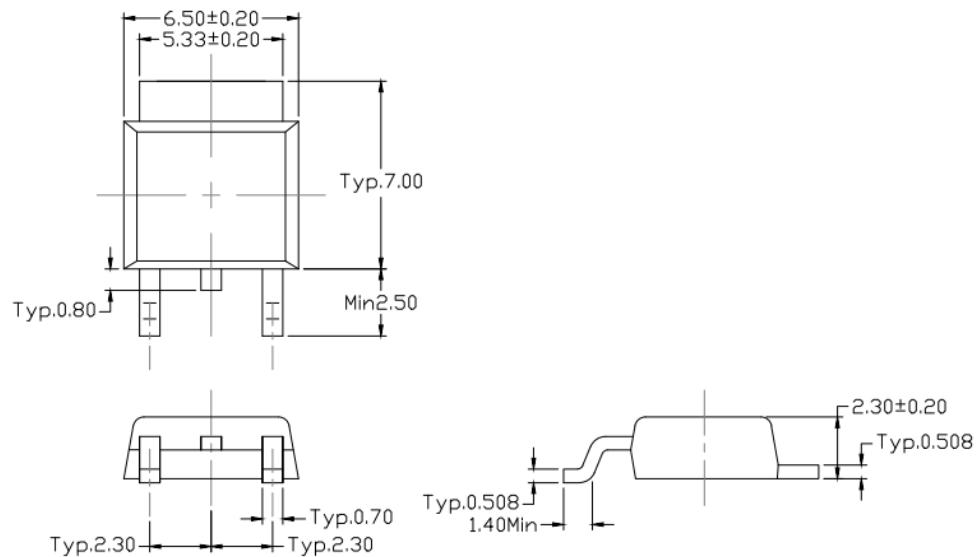




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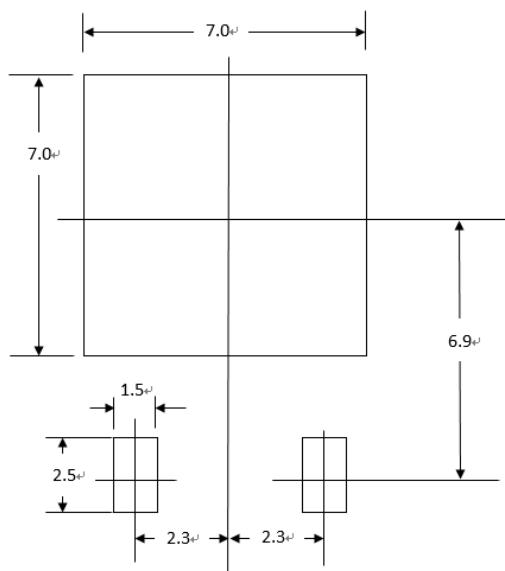
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### Package Dimension (TO-252)



Dimensions in mm unless otherwise stated

### Recommended pad layout for surface mount leadform



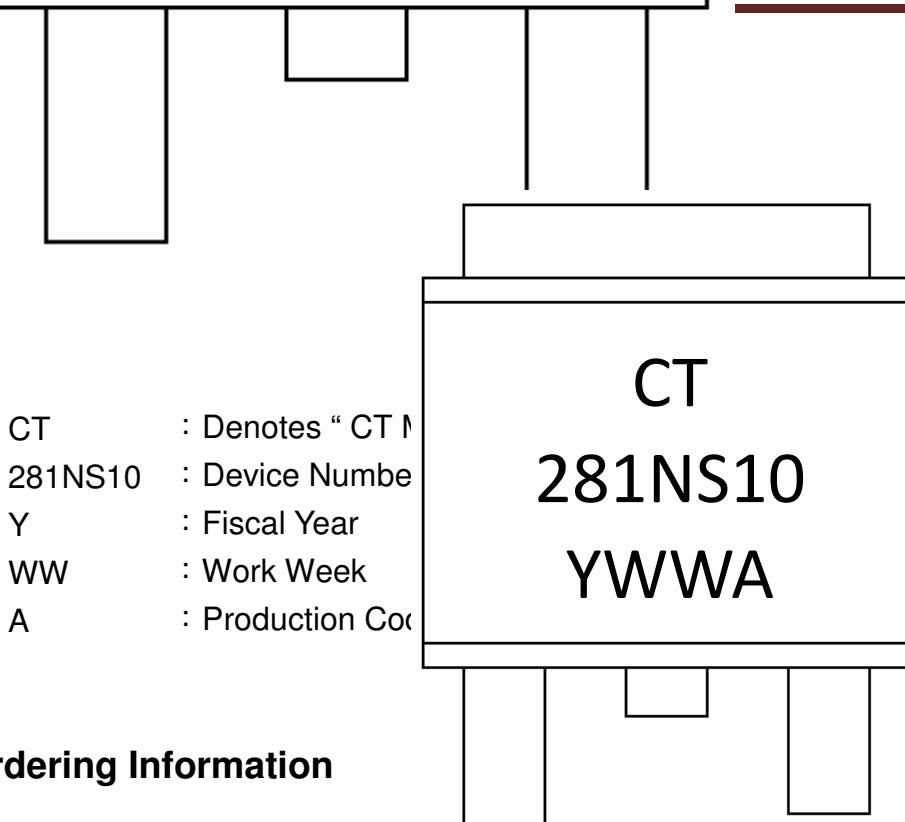
Dimensions in mm unless otherwise stated

# CTL281NS10-T52

## YWWA

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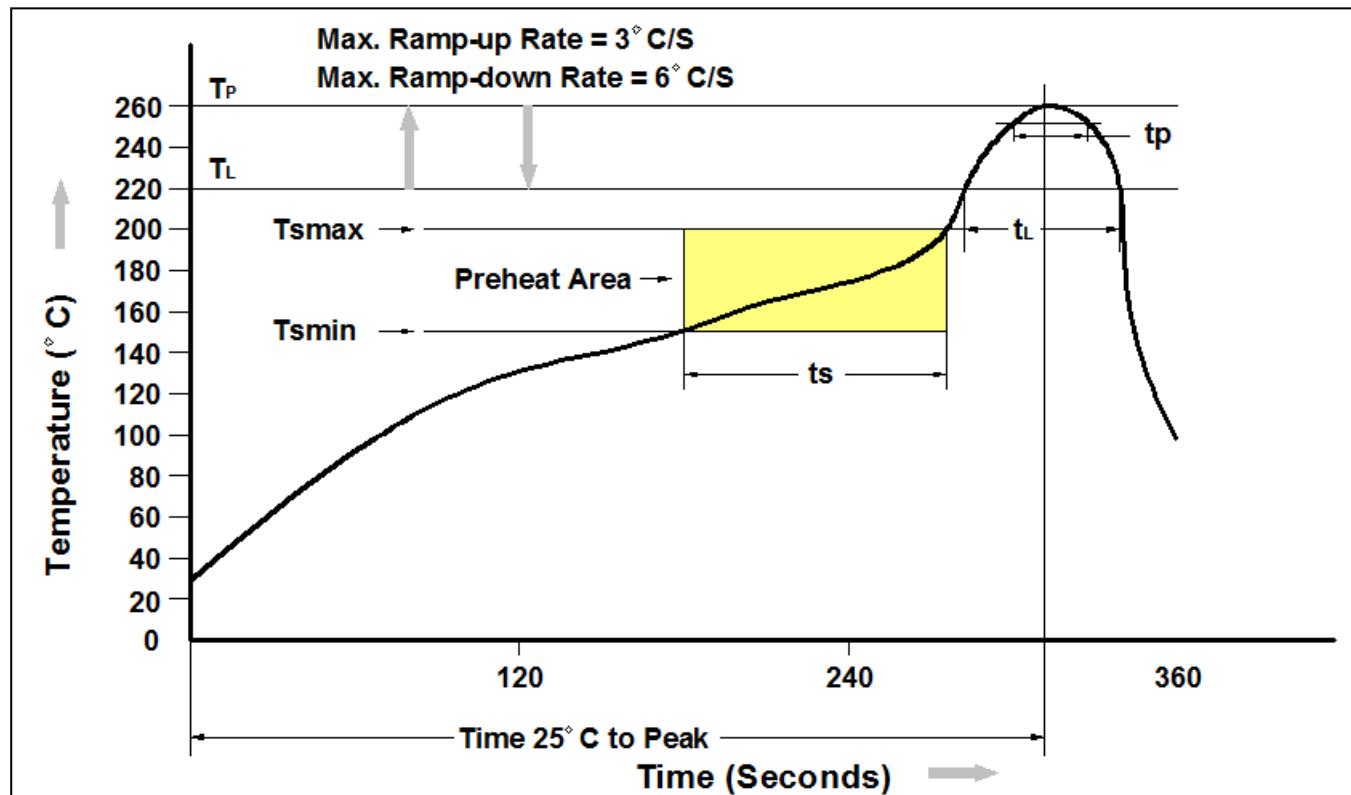
### Ordering Information

Part Number	Description	Quantity
CTL281NS10-T52	TO-252 Reel	2500 pcs



## N-Channel Enhancement MOSFET

## Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tp)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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